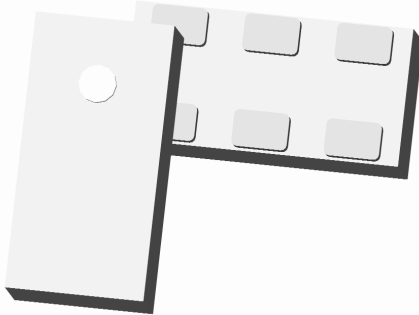


Xinger®



Ultra Low Profile 0603 RF Crossover

Description

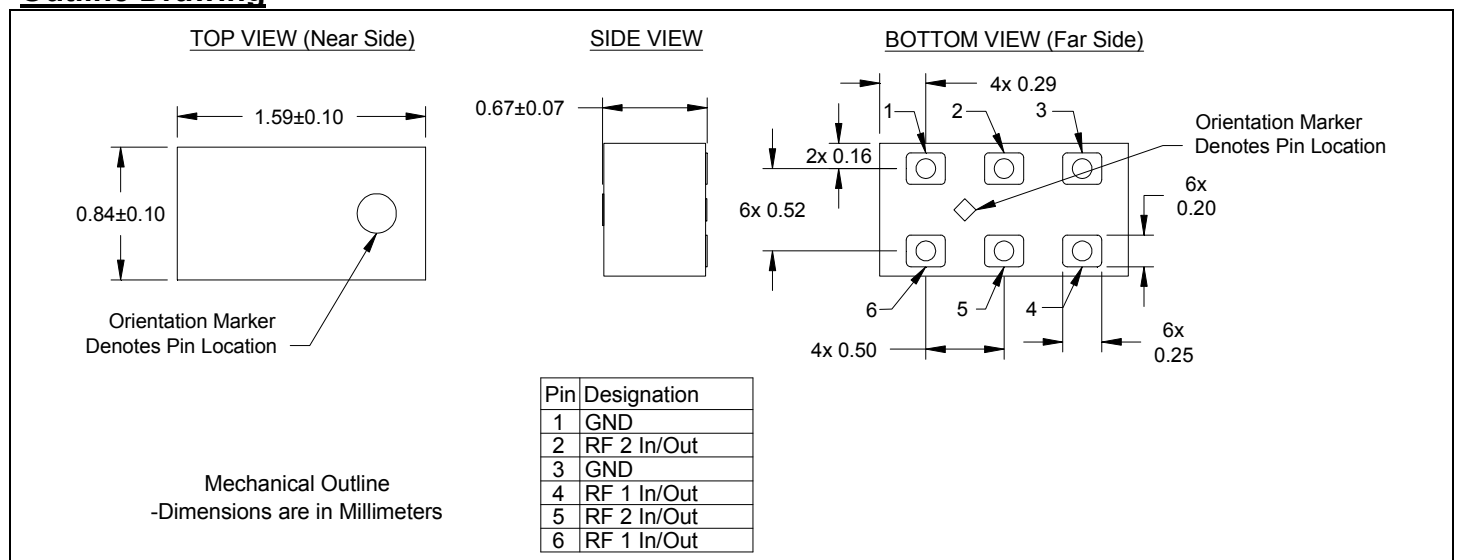
The (patent pending) is an ultra-small low profile crossover that enables the transition of two intersecting RF traces in an easy to use industry standard SMT package. The 0603 crossover is ideal for any critical applications where layout and available space are a premium and resorting to additional PWB layers and larger overall footprints are unacceptable. With low insertion loss and high isolation packaged with cost in mind, this novel component delivers.

The X0060L7575AHF is available on tape and reel for pick and place high volume manufacturing. All of the Xinger components are constructed from ceramic filled PTFE composites which possess excellent electrical and mechanical stability. All parts have been subjected to rigorous qualification testing and units are 100% RF tested.

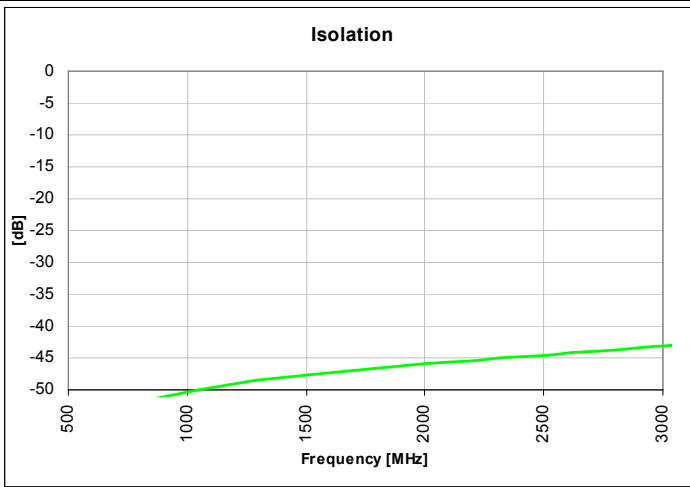
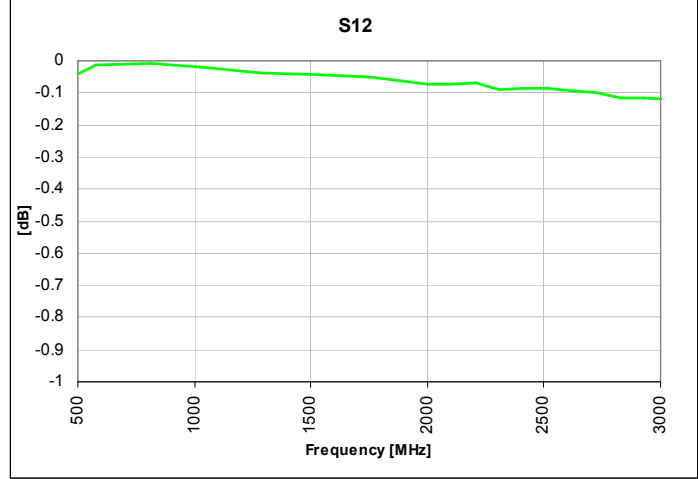
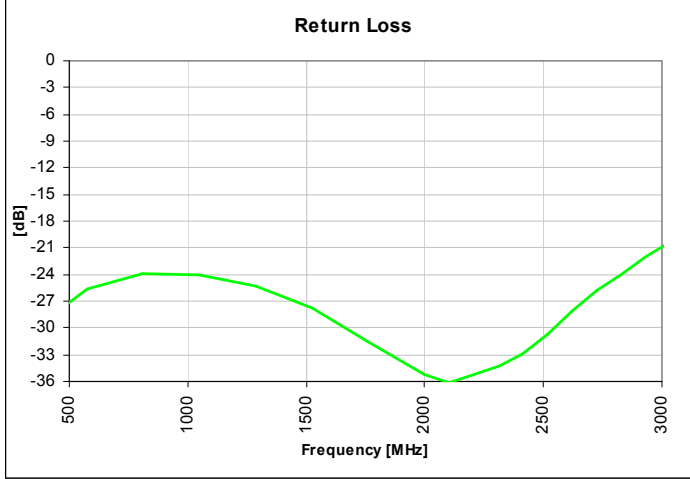
Detailed Electrical Specifications*: Specifications subject to change without notice.

Features:	Parameter	ROOM (25°C)			Unit
		Min.	Typ.	Max	
• 0 – 2500 MHz.	Frequency	0		2500	MHz
• 0.7mm Height Profile	Port Impedance		75		Ω
• 75 Ohm RF-RF Crossover	Return Loss	19	21		dB
• All Wireless Frequencies	Insertion Loss		0.1	0.15	dB
• Low Insertion Loss	Isolation (cross-talk)				
• High Isolation		0 – 700 MHz	44	52	dB
• Surface Mountable		700 - 1700 MHz	40	47	dB
• Tape & Reel	1700 - 2500 MHz	38	43		dB
• Non-conductive Surface	Power Handling			2	Watts
• RoHS Compliant	Operating Temperature	-55		+85	°C
• Halogen Free					

Outline Drawing



Typical Broadband Performance: 0 GHz. to 3.0 GHz.



Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.



Circuit Pattern

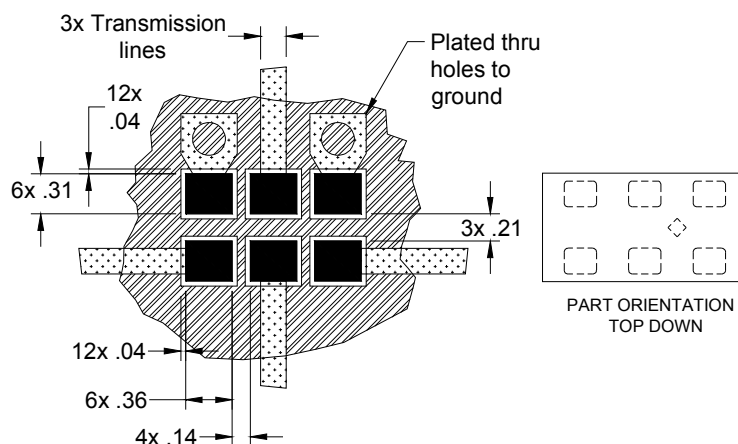


Footprint Pad (s)



Solder Resist

Dimensions are in Millimeters
Mounting Footprint



Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-2. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel. See Model Numbers below for further ordering information.

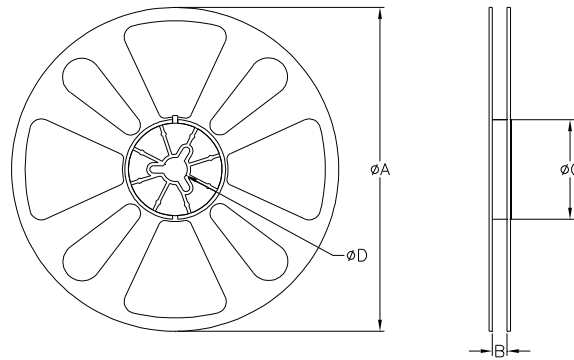
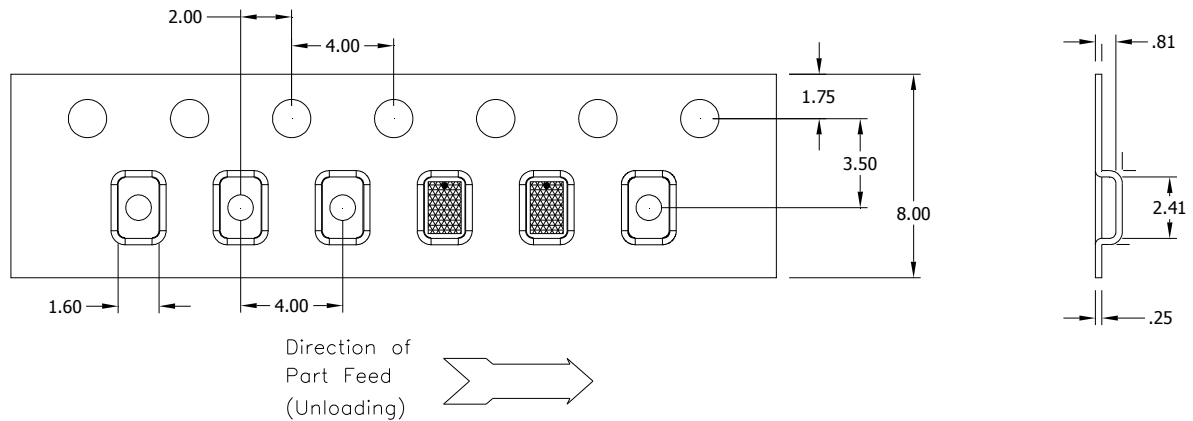


TABLE 1		
QUANTITY/REEL	REEL DIMENSIONS mm	
4000	ϕA	177.80
	B	8.00
	ϕC	50.80
	ϕD	13.00